



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB180N06S4-H1		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000980508						
<b>Package</b>		PG-TO263-7-3		<b>Weight*</b>		1539.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.427	0.68	0.68	6771	6771
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156	
	non noble metal	copper	7440-50-8	801.714	52.04	52.11	520617	521295
wire	non noble metal	aluminium	7429-90-5	123.345	8.01	8.01	80098	80098
encapsulation	organic material	carbon black	1333-86-4	7.166	0.47		4654	
	plastics	epoxy resin	-	78.828	5.12		51190	
	inorganic material	silicondioxide	60676-86-0	391.754	25.44	31.03	254398	310242
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	7998	7998
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175
solder	noble metal	silver	7440-22-4	0.168	0.01		109	
	non noble metal	tin	7440-31-5	0.134	0.01		87	
	non noble metal	lead	7439-92-1	6.412	0.42	0.44	4164	4360
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.90	6.91	68971	69061
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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